

- z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.
- z25 ■ If Sil-Pad part number GP1500-0.020-00-0404 is used, the pads need to be cut into 2 inch squares.
- z26 ■ Apply thin layer of SA-1000 between Aluminum Plate MCH003 and PCB during installation
- z27 ■ See PWR045 Assembly Guide for build up on L1 and associated hardware

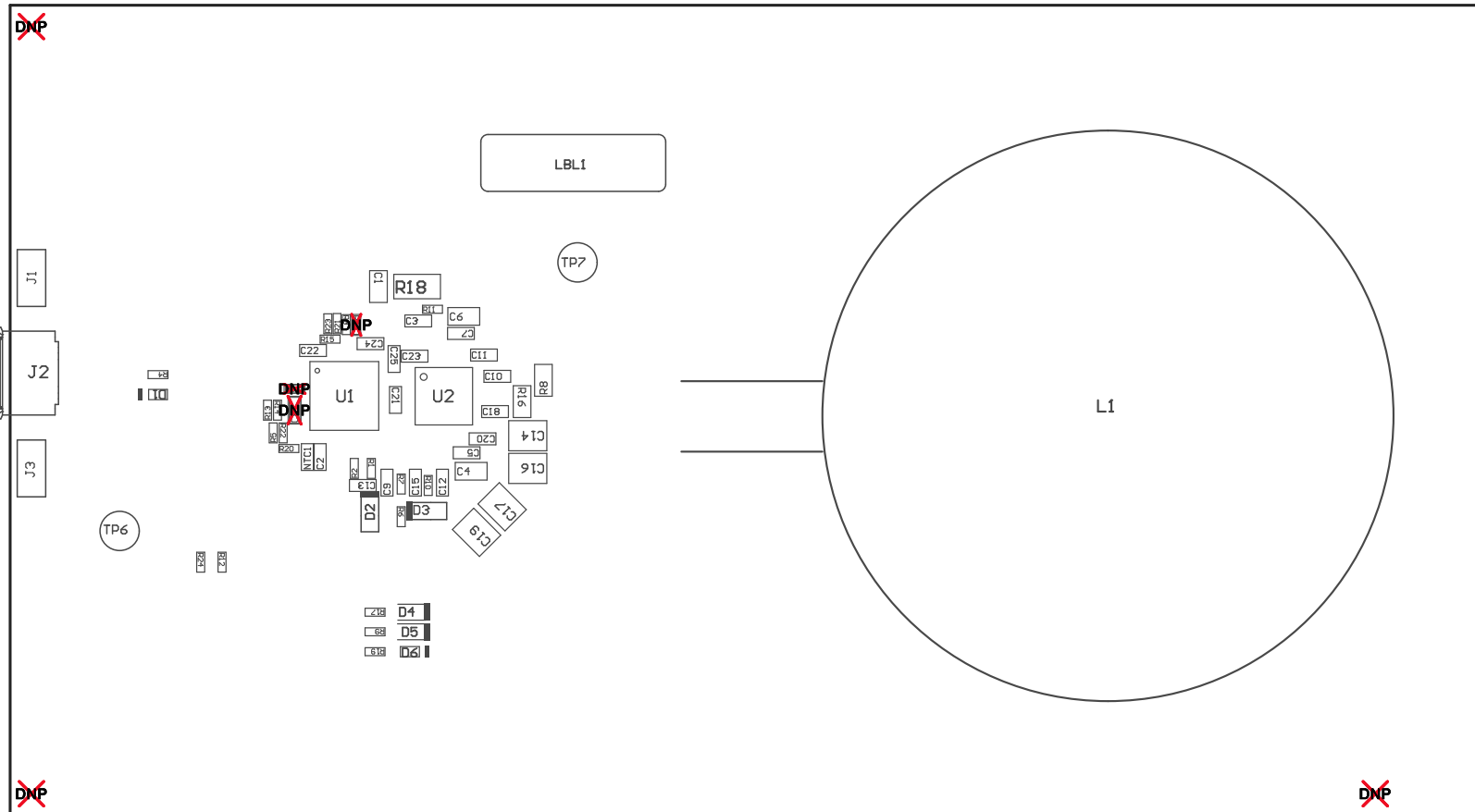
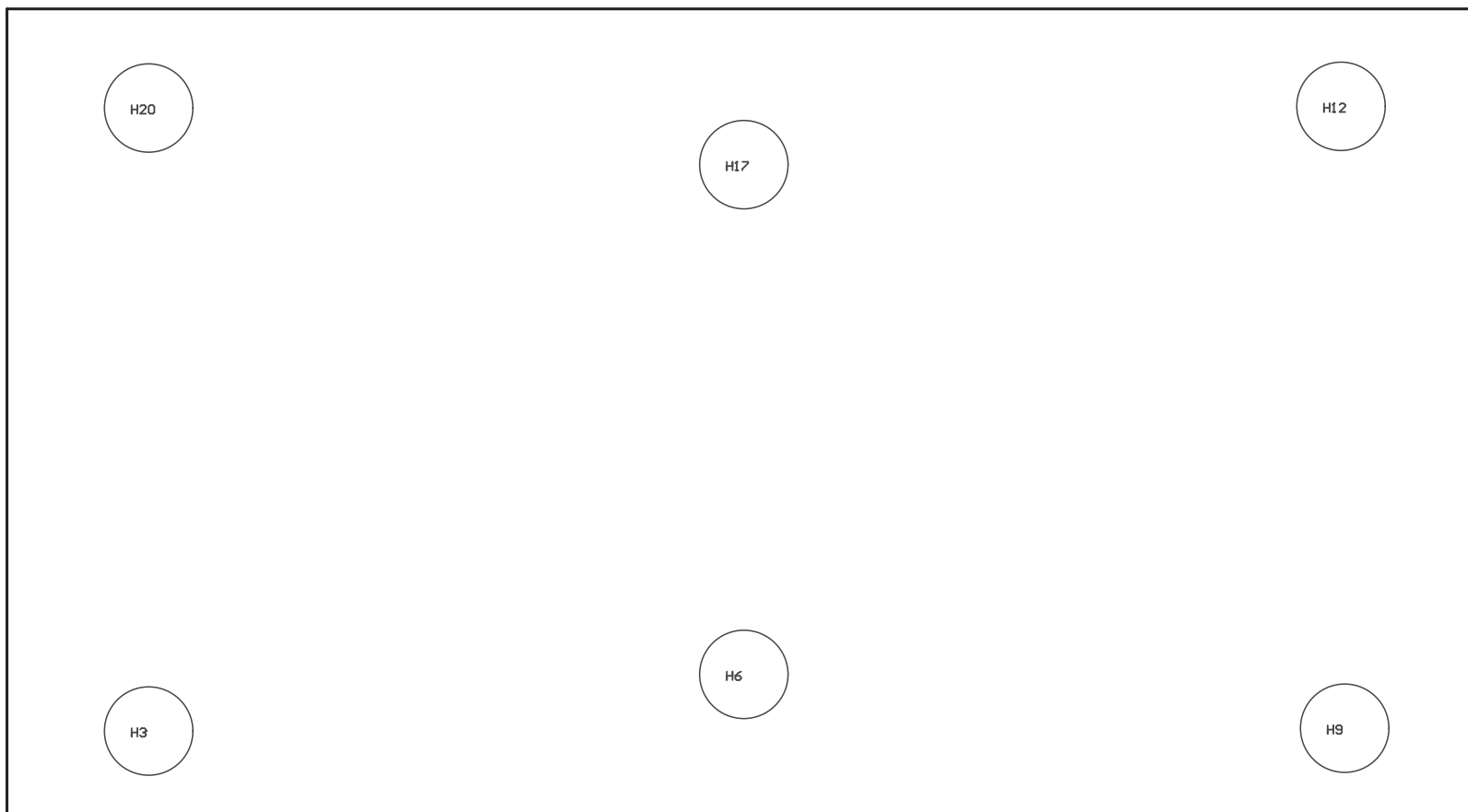


TABLE 1

Variant	Label text
001	bq50002 + bq500511

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00623	REV: E1	SUN REV: Not In VersionControl
IGNORE ->			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/15/2015 8:47:10 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00623	REV: E1	SUN REV: Not In VersionControl
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/15/2015 8:47:11 PM	TEXAS INSTRUMENTS	

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